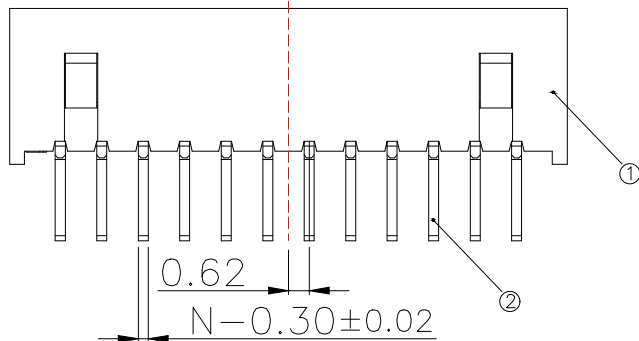
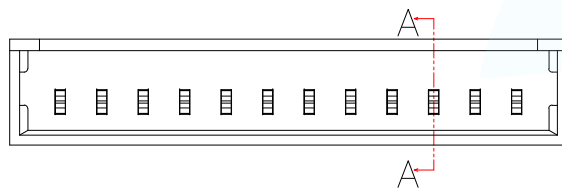
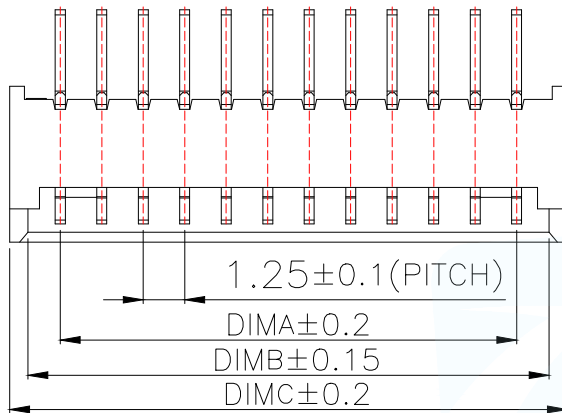


LOCK CONFIGURATION (锁扣位置)



序号	品名	材质
1	1.25 Pitch S/T Wire To Board Housing DIP(H=4.7)	PA66 UL94V-2 Red
2	1.25 Pitch S/T Wire To Board Terminal DIP(H=4.7)	Copper Alloy/ Tin Plating

Technical Index:

1.The surface of the plastic parts should be smooth,no rough edges,no obvious shrinkage,defects,cracks and other phenomena)

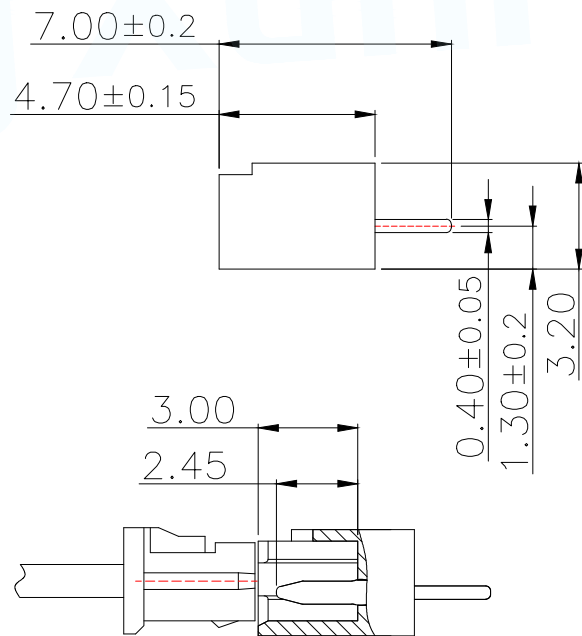
2.Lock Configuration: 2 to 3Pin is 1, ≥ 4Pin is 2

3.Temperature range: -25°C~+85°C.

4.Rated voltage: 125V, AC/DC.

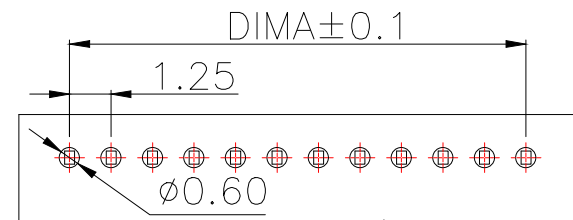
5.Contact resistance: ≤0.02Ω.

6.Insulation resistance: ≥100MΩ



SECTION A-A

Part No	Pin	A	B	C
WAFER-MX1.25-2PZZ-R62	2	1.25	3.20	4.30
WAFER-MX1.25-3PZZ-R62	3	2.50	4.45	5.55
WAFER-MX1.25-4PZZ-R62	4	3.75	5.70	6.80
WAFER-MX1.25-5PZZ-R62	5	5.00	6.95	8.05
WAFER-MX1.25-6PZZ-R62	6	6.25	8.20	9.30
WAFER-MX1.25-7PZZ-R62	7	7.50	9.45	10.55
WAFER-MX1.25-8PZZ-R62	8	8.75	10.70	11.80
WAFER-MX1.25-9PZZ-R62	9	10.00	11.95	13.05
WAFER-MX1.25-10PZZ-R62	10	11.25	13.20	14.30
WAFER-MX1.25-11PZZ-R62	11	12.50	14.45	15.55
WAFER-MX1.25-12PZZ-R62	12	13.75	15.70	16.80
WAFER-MX1.25-13PZZ-R62	13	15.00	16.95	18.05
WAFER-MX1.25-14PZZ-R62	14	16.25	18.20	19.30
WAFER-MX1.25-15PZZ-R62	15	17.50	19.45	20.55
WAFER-MX1.25-16PZZ-R62	16	18.75	20.70	21.80
WAFER-MX1.25-17PZZ-R62	17	20.00	21.95	23.05
WAFER-MX1.25-18PZZ-R62	18	21.25	23.20	24.30
WAFER-MX1.25-19PZZ-R62	19	22.50	24.45	25.55
WAFER-MX1.25-20PZZ-R62	20	23.75	25.70	26.80



胶芯外形

适用线路板(PCB LAYOUT)

MANUFACTURE DWG			 东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	
UNLESS OTHERWISE SPECIFIED TOLERANCES			TITLE:1.25 PITCH H4.7 S/T WIRE TO BOARD DIP CONN.	
DECIMALS:	ANGLES:	PAR	WAFER-MX1.25-NPZZ-R62	
X.:±0.50	X':.:±5°	DWN		
.X:±0.20	X.X':.:±3°	CHKD		
.XX:±0.10	X.XX':.:±1°	APVD		
CUSTOMER COPY		SCALE:1:1	UNIT:MM	
		SIZE:A4	SHEET:1F1	REV:A